Park Advanced Circuitry Materials

Nelco[®] N4000-12 Nelco[®] N4000-12 SI[®]





High Speed / Low Loss, CAF Resistant Laminate & Prepreg

The Nelco® N4000-12 series is an enhanced epoxy resin system designed for use in high speed, low loss applications requiring thermal stability, excellent signal speed and CAF resistance².

Key Features

Lead-Free Assembly Compatible

Suitable for assemblies with a maximum reflow temperature of 245
260°C¹

Tg >190°C, robust thermal stability

- Designed for high-reliability assemblies demanding wide bandwidth and increased thermal performance
- $T_{260} > 60$ minutes
- Low Z-Axis CTE

High Speed and Low Loss Properties

- Appropriate for applications in the 1-10 GHz range
- Low Df and Dk allows for low signal distortion and faster signal propagation for high frequency and high reliability applications

CAF² Resistant

- The low Z-CTE and proven CAF resistance² provide long-term reliability for both RF and digital applications

SI (Signal Integrity) option

- When used, SI glass provides enhanced electrical performance for even the most demanding applications

High-Tg FR-4 processing

- Processes similar to traditional high Tg FR-4 materials
- Provides excellent drilling
- Chemical desmear compatible
- 75 min press at 193°C and 200-300 psi.

And Much More

- Vacuum laminated
- Available in a wide variety of constructions, copper weights and glass styles including standard copper, double treat and RTFOIL*
- Meets UL 94V-0 and IPC-4101/29 specifications
- All Nelco® materials are RoHS compliant.



Applications

- Lead-Free Assemblies
- Fine-Line Multilayers
- Backplanes
- Surface-Mount Multilayers
- BGA Multilayers
- SIPs
- MCM-Ls
- Direct Chip Attach
- Network Storage
- Wireless Communications Infrastructure
- High Speed Computing

Global Availability

Nelco Products, Inc. (California) - Americas

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Park's UL file number: E36295

Nelco[®] N4000-12 and N4000-12 SI[®]

High Speed / Low Loss, CAF Resistant Laminate & Prepreg

Mechanical Properties	N4000-12	-12 SI	U.S. Units	N4000-12	-12 SI	Metric	Test Method
Peel Strength - 1 oz. (35 micron) Cu	1000 12	.2 0.	olor ollito	1000012	12 01	mouro	Tool mound
After Solder Float	9.2	9.2	lb / inch	1.61	1.61	N / mm	IPC-TM-650.2.4.8
At Elevated Temperature	8.7	8.7	lb / inch	1.53	1.53	N / mm	IPC-TM-650.2.4.8.2a
After Exposure to Process Solutions	9.3	9.3	lb / inch	1.62	1.62	N / mm	IPC-TM-650.2.4.8
X / Y CTE [-40°C to +125°C]		0.0	,	12 - 15.5	12 - 15.5	ppm / °C	IPC-TM-650.2.4.41
Z Axis CTE Alpha 1 [50°C to Tg]				60	60	ppm / °C	IPC-TM-650.2.4.24
Z Axis CTE Alpha 2 [Tg to 260°C]				260	260	ppm / °C	IPC-TM-650.2.4.24
Z Axis Expansion [50°C to 260°C]	3.6	3.6	%	3.6	3.6	%	IPC-TM-650.2.4.24
Young's Modulus (X / Y)	4.1 / 3.4	TBD	psi x 10 ⁶	28.3 / 23.4	TBD	GN / m ²	ASTM D3039
Poisson's Ratios (X / Y)	0.16 / 0.14	TBD	por x To	0.16 / 0.14	TBD	0.17 111	ASTM D3039
Thermal Conductivity	0.107 0.11	100		0.3 - 0.5	0.29	W / mK	ASTM E1461
Specific Heat				1.20	1.14	J/gK	ASTM E1461
'				1.20	1.17	o / git	NOTHI E1401
Electrical Properties							
Dielectric Constant (50% resin content)	0.7	2.4		2.7	2.4		IPC-TM-650.2.5.5.9
@ 1 GHz (RF Impedance)	3.7	3.4		3.7	3.4		
@ 10 GHz (Stripline)	3.6	3.3		3.6	3.3		IPC-TM-650.2.5.5.5
@ 10 GHz (Split Post Cavity)	3.7	3.3		3.7	3.3		
Dissipation Factor (50% resin content)	0.000	0.000		0.000	0.000		
@ 2.5 GHz (Split Post Cavity)	0.008	0.006		0.008	0.006		
@ 10 GHz (Split Post Cavity)	0.008	0.007		0.008	0.007		
Volume Resistivity				408	408	MΩ - cm	IDO TIA 050 0 5 47 4
C - 96 / 35 / 90				10 ⁸	10 ⁸		IPC-TM-650.2.5.17.1
E - 24 / 125				10 ⁷	10 ⁸	$M\Omega$ - cm	IPC-TM-650.2.5.17.1
Surface Resistivity	407	407	мо	407	407	МО	IDO TIM 050 0 5 47 4
C - 96 / 35 / 90	10 ⁷	10 ⁷	МΩ	10 ⁷	10 ⁷	МΩ	IPC-TM-650.2.5.17.1
E - 24 / 125	10 ⁶	10 ⁶	MΩ	10 ⁶	10 ⁶	MΩ	IPC-TM-650.2.5.17.1
Electric Strength	1470	TBD	V / mil	5.8x10 ⁴	TBD	V / mm	IPC-TM-650.2.5.6.2
Dielectric Breakdown	>50	>50	kV .	>50	>50	kV .	IPC-TM-650.2.5.6
Arc Resistance	65	65	seconds	65	65	seconds	IPC-TM-650.2.5.1
Thermal Properties							
Glass Transition Temperature (Tg)							
DSC (°C)	374	374	°F	190	190	°C	IPC-TM-650.2.4.25c
TMA (°C)	356	356	°F	180	180	°C	IPC-TM-650.2.4.24c
DMA (°C) (Tan d Peak)	410	410	°F	210	210	°C	IPC-TM-650.2.4.24.3
Degradation Temp (TGA) (5% wt. loss)	662	662	°F	350	350	°C	IPC-TM-650.2.4.24.6
Pressure Cooker-60 min then solder dip							IPC-TM-650.2.6.16
@288°C until failure (max 10 min.)	Pass	Pass		Pass	Pass		(modified)
T260	>60	>60	minutes	>60	>60	minutes	IPC-TM-650.2.4.24.1
Chemical / Physical Properties							
Moisture Absorption	0.09	0.09	wt. %	0.09	0.09	wt. %	IPC-TM-650.2.6.2.1
Methylene Chloride Resistance	1.0	1.0	% wt. chg.	1.0	1.0	% wt. chg.	IPC-TM-650.2.3.4.3
Density [50% resin content]				1.90	1.78	g / cm ³	Internal Method

Park Electrochemical Corp. is a global advanced materials company which develops and manufactures high-technology digital and RF/microwave printed circuit materials and advanced composite materials. The company operates under the Nelco®, Nelcote® and Nova™ names. All test data provided are typical values and not intended to be specification values. For review of critical specification tolerances, please contact a Nelco representative directly. Nelco reserves the right to change these typical values as a natural process of refining our testing equipment and techniques. Nelco reserves the right to make changes without further notice to any products herein to improve reliability, function or design. Nelco does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights nor the rights of others. This disclaimer of warranty is in lieu of all warranties whether expressed, implied or statutory, including implied warranties of merchantability or fitness for a particular purpose.

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¹Refer to the N4000-12 Best Practices document and Contract Manufacturing Q&A for PCB processing recommendations. Visit www.parkelectro.com for more information. ²CAF resistance has been established to greater than 500 hours using a specific OEM coupon design and test procedure. Visit www.parkelectro.com for more information.

